

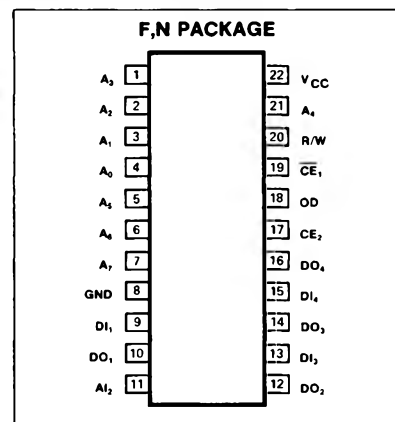
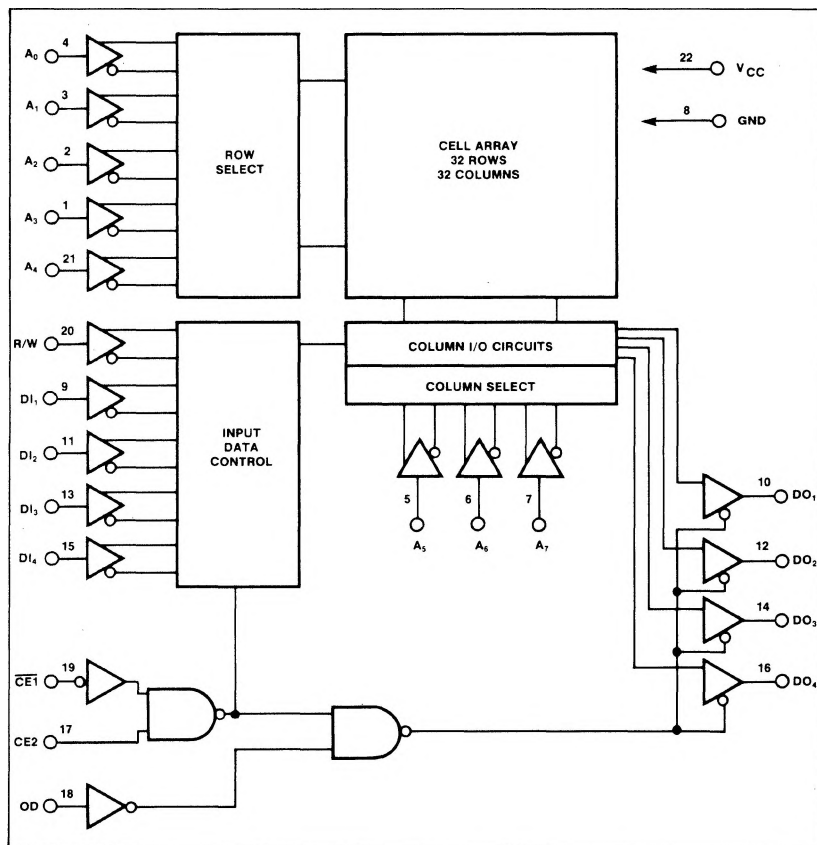
DESCRIPTION

The 2101 series is high performance, low power static read/write RAM's.

The 2101 series is fabricated with n-channel silicon gate technology which allows the design of high performance easy to use MOS circuits and provides a high functional density on a given monolithic chip.

FEATURES

- Fully static
- No refresh operations, sense amps or clocks required
- All inputs and outputs are TTL compatible
- One 5V power supply required

PIN CONFIGURATION**BLOCK DIAGRAM****ABSOLUTE MAXIMUM RATINGS¹**

PARAMETER	RATING	UNIT
T _A	Temperature range	°C
T _{STG}	Operating under bias	0 to 70
	Storage	-65 to 150
P _D	Power dissipation	1
	Voltage on any pin with respect to ground	-0.5 to 7
		W
		V

DC ELECTRICAL CHARACTERISTICS $T_A = 0^\circ\text{C}$ to 70°C , $V_{CC} = 5\text{V} \pm 5\%$, unless otherwise specified

PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ ²	Max	
Input voltage V_{IL} Low V_{IH} High		-0.5 2.2		0.65 V_{CC}	V
Output voltage V_{OL} Low V_{OH} High	$I_{OL} = 2.0\text{mA}$ $I_{OH} = 150\mu\text{A}$			0.45	V
I_{LI} Input current	$V_{IN} = 0$ to 5.25V			10	μA
I/O leakage current ³ I_{LOH} I_{LOL}	$CE_1 = 2.2\text{V}$ $V_{OUT} = 4.0\text{V}$ $V_{OUT} = 0.45\text{V}$			15 -50	μA
Supply current I_{CC1} I_{CC2}	$V_{IN} = 5.25\text{V}$, $I_O = 0\text{mA}$ $T_A = 25^\circ\text{C}$ $T_A = 0^\circ\text{C}$		30	60 70	mA
Capacitance ³ C_{IN} Input (All pins) C_{OUT} Output	$V_{IN} = 0\text{V}$ $V_{OUT} = 0\text{V}$		4 8	8 12	pF

AC ELECTRICAL CHARACTERISTICS $T_A = 0^\circ\text{C}$ to 70°C , $V_{CC} = 5\text{V} \pm 5\%$, Input pulse levels = $+0.65\text{V}$ to 2.2V , Input pulse rise and fall times = 20ns , Timing measurement reference level = 1.5V , Output load = 1 TTL gate and $C_L = 100\text{pF}$, unless otherwise specified.

PARAMETER	TO	FROM	2101			2101-1			2101-2			UNIT
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
READ CYCLE												
t_{RC} Read cycle			1,000			500			650			ns
t_A Access time					1,000			500			650	ns
t_{CO}					800			350			400	ns
t_{OD}					700			300			350	ns
t_{DF}^4			0		200	0		150	0		150	ns
t_{OH} Previous read data valid after change of address	Output Output High Z state	Chip enable Output disable Data output	40			40			40			ns
WRITE CYCLE												
t_{WC} Write cycle			1,000			500			650			ns
t_{AW} Write delay			150			100			150			ns
t_{CW}	Write	Chip enable	900			400			550			ns
Setup and hold time												ns
t_{DW} Setup time	Rise of R/W	Data in	700			280			400			
t_{DH} Hold time	Change of data in	Rise of R/W	100			100			100			
t_{DS} Setup time	Output	Output disable	200			150			150			
t_{WP} Write pulse			750			300			400			ns
t_{WR} Write recovery			50			50			50			ns

NOTES

- Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- Typical values are for $T_A = 25^\circ\text{C}$ and typical supply voltage.
- This parameter is periodically sampled and is not 100% tested.
- t_{OF} is with respect to the trailing edge of CE_1 , CE_2 or OD , whichever occurs first.
- CD should be tied low for separate I/O operation.

TIMING DIAGRAMS

